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A - [001] 011 04- 140 23& 231 236 316 359 431 445 477 609 623 627 678 720  
722

AP - JP19800049686 19800415

CPY - MATU

DC - A85 L03

FS - CPI

IC - H01C7/00 ; H01C17/28 ; H01G1/01 ; H01G4/12 ; H01L21/28 ; H01L41/00

KS - 0231 1277 1996 2198 2200 2318 2440 2682 2729 2743 2857

MC - A12-E07B A12-E07V A12-W12D L03-A01A L03-B03

PA - (MATU ) MATSUSHITA ELEC IND CO LTD

PN - JP56146218 A 19811113 DW198152 004pp

- JP63004331B B 19880128 DW198808 000pp

PR - JP19800049686 19800415

XIC - H01C-007/00 ; H01C-017/28 ; H01G-001/01 ; H01G-004/12 ; H01L-021/28 ;  
H01L-041/00

AB - J56146218 Ag cpd. paste contg. 0.005-30 wt.% of Ag is coated on a dielectric ceramic substrate except for edge portions. The Ag cpd. paste on the substrate is heat-treated at 350-850 deg.C. to form Ag layers. The Ag layers are electroless-plated with Cu to form metal electrodes.

- Pref. the Ag cpd. is AgNO<sub>3</sub>, Ag<sub>2</sub>CO<sub>3</sub>, Ag acetate or Ag cyanide. Specifically, Ag cpd. paste is produced by mixing AgNO<sub>3</sub>, phenol resin as a binder and ethyl cellulose as a solvent. The Ag cpd. paste contains 3 wt.% of Ag and has a viscosity of 30,000-60,000 CSP. The paste is coated on both sides of a dielectric ceramic disk, dried at 80-100 deg.C. and fired at 600 deg.C to form Ag layers. The Ag layers are plated with Cu.

- Cost of electrodes on electronic part e.g. a capacitor is reduced.

IW - PRODUCE ELECTRODE DIELECTRIC CERAMIC COATING CERAMIC SUBSTRATE SILVER  
BASED PASTE HEAT TREAT ELECTROLESS PLATE COPPER

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NC - 001

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ORD - 1981-11-13

PAW - (MATU ) MATSUSHITA ELEC IND CO LTD

TI - Prodn. of electrode for dielectric ceramic - by coating ceramic substrate with silver based paste, heat treating and electrolessly plating with copper